

SOT1447-1

wafer level chip-scale package; 99 bumps; 4.37 x 3.82 x 0.5 mm

21 April 2016

Package information

1. Package summary

| | |
|---------------------------------------|---------------------------------------|
| Terminal position code | B (bottom) |
| Package type descriptive code | WLCSP99 |
| Package type industry code | WLCSP99 |
| Package style descriptive code | WLCSP (wafer level chip-size package) |
| Package style suffix code | NA (not applicable) |
| Mounting method type | S (surface mount) |
| Issue date | 26-6-2015 |

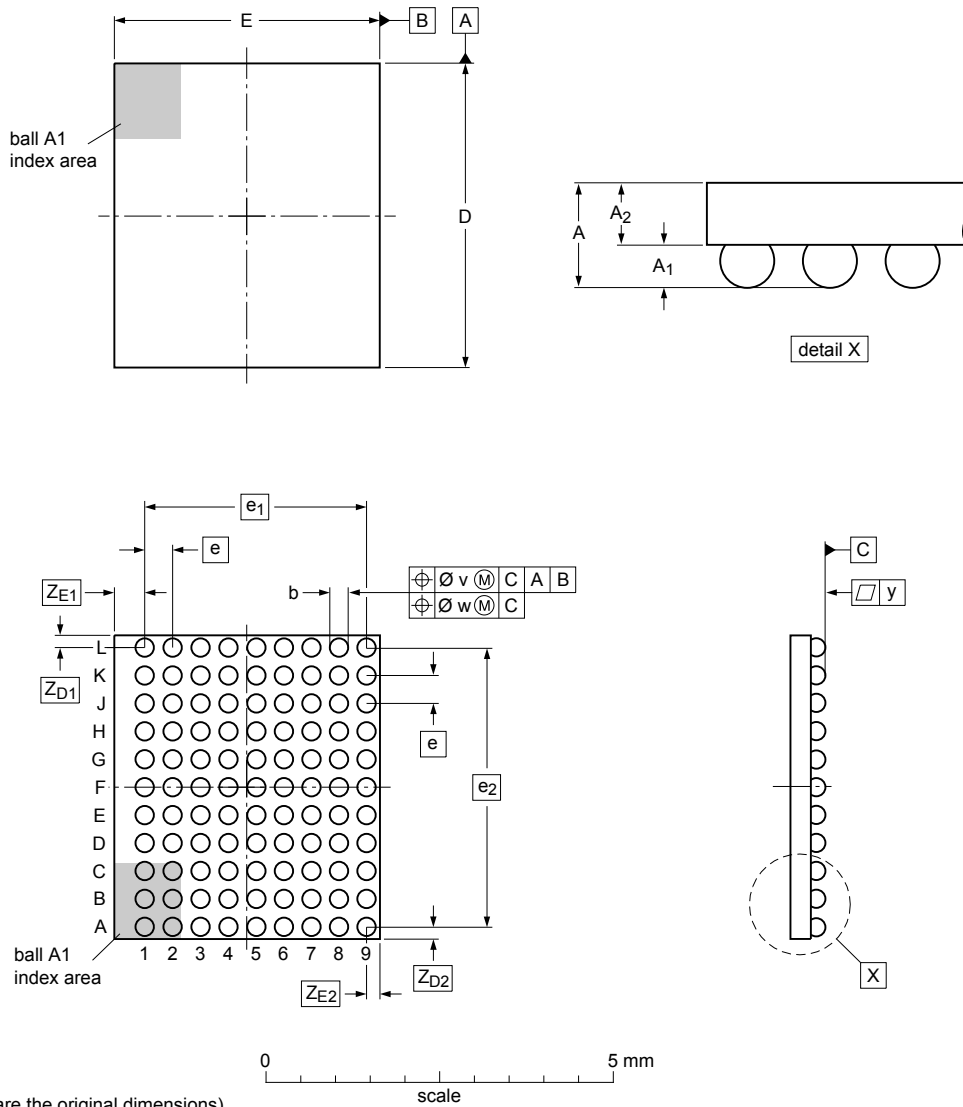
Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|------|-----|------|------|------|
| D | package length | 4.34 | - | 4.37 | 4.4 | mm |
| E | package width | 3.79 | - | 3.82 | 3.85 | mm |
| A | seated height | 0.46 | - | 0.5 | 0.54 | mm |
| A ₂ | package height | 0.28 | - | 0.3 | 0.32 | mm |
| e | nominal pitch | - | - | 0.4 | - | mm |
| n ₂ | actual quantity of termination | - | - | 99 | - | |



2. Package outline

WLCSPP99: wafer level chip-scale package; 99 bumps; 4.37 x 3.82 x 0.5 mm SOT1447-1



Dimensions (mm are the original dimensions)

| Unit | A | A ₁ | A ₂ | b | D | E | e | e ₁ | e ₂ | Z _{D1} | Z _{D2} | Z _{E1} | Z _{E2} | v | w | y |
|--------|------|----------------|----------------|------|------|------|-----|----------------|----------------|-----------------|-----------------|-----------------|-----------------|------|-------|------|
| max | 0.54 | 0.23 | 0.325 | 0.29 | 4.40 | 3.85 | | | | | | | | | | |
| mm nom | 0.50 | 0.20 | 0.300 | 0.26 | 4.37 | 3.82 | 0.4 | 3.2 | 4.0 | 0.185 | 0.185 | 0.435 | 0.185 | 0.05 | 0.015 | 0.03 |
| min | 0.46 | 0.17 | 0.275 | 0.23 | 4.34 | 3.79 | | | | | | | | | | |

sot1447-1_po

| Outline version | References | | | European projection | Issue date |
|-----------------|------------|-------|-------|---------------------|------------------------|
| | IEC | JEDEC | JEITA | | |
| SOT1447-1 | | | | | -15-06-26- 15-11-11 |

Fig. 1. Package outline WLCSPP99 (SOT1447-1)

3. Legal information

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